CategoryTOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSII)/Category

SSM6K08FU

High Speed Switching Applications

Unit: mm

• Small package

• Low on resistance: $R_{on} = 105 \text{ m}\Omega \text{ (max) (@V_{GS} = 4 V)}$

 $R_{on} = 140 \text{ m}\Omega \text{ (max) (@VGS} = 2.5 \text{ V)}$

• High-speed switching: ton = 16 ns (typ.)

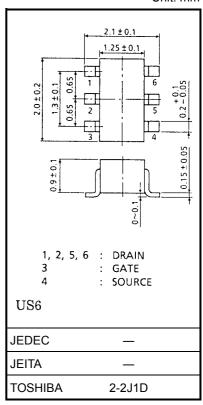
 $t_{off} = 15 \text{ ns (typ.)}$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		V _{DS}	20	V	
Gate-Source voltage		V _{GSS}	±12	V	
Drain current	DC	I _D	1.6	Α	
	Pulse	I_{DP}	3.2		
Drain power dissipation		P _D (Note1)	300	mW	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

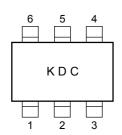
Note1: Mounted on FR4 board.

(25.4 mm \times 25.4 mm \times 1.6 t, Cu Pad: 0.32 mm² \times 6) Figure 1.

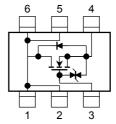


Weight: 6.8 mg (typ.)

Marking Circuit (top view)



Equivalent



Handling Precaution

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

Electrical Characteristics (Ta = 25°C)

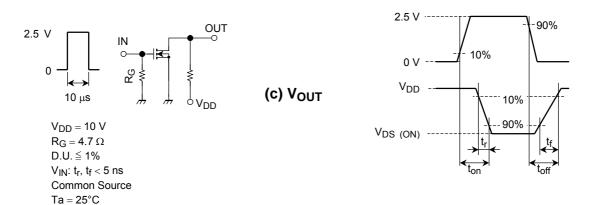
Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage curr	ent	I _{GSS}	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$	_	_	±1	μА	
Drain Course breekdown voltage		V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0$	20	_	_	V	
Drain-Source breakdown voltage	V (BR) DSX	$I_D = 1 \text{ mA}, V_{GS} = -12 \text{ V}$	12	_	_	V		
Drain cut-off curre	ent	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0	_	_	1	μА	
Gate threshold vo	Itage	V _{th}	$V_{DS} = 3 \text{ V}, I_D = 0.1 \text{ mA}$	0.5	_	1.2	V	
Forward transfer a	admittance	Y _{fs}	$V_{DS} = 3 \text{ V}, I_D = 0.8 \text{ A}$ (Note:	2) 2.0	_	_	S	
Drain-Source ON resistance		R _{DS} (ON)	$I_D = 0.8 \text{ A}, V_{GS} = 4 \text{ V}$ (Note:	2) —	77	105	mΩ	
			I _D = 0.8 A, V _{GS} = 2.5 V (Note2	2) —	100	140		
			I _D = 0.8 A, V _{GS} = 2.0 V (Note2	2) —	125	210		
Input capacitance	acitance C_{iss} $V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		_	306	_	pF		
Reverse transfer capacitance C _{rss}		$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		44	_	pF		
Output capacitance		C _{oss}	V _{DS} = 10 V, V _{GS} = 0, f = 1 MHz	_	74	_	pF	
Switching time	Turn-on time	t _{on}	$V_{DD} = 10 \text{ V}, I_D = 0.8 \text{ A},$	_	16	_	ns	
	Turn-off time	t _{off}	$V_{GS} = 0~2.5 \text{ V}, R_G = 4.7 \Omega$	_	15	_		

Note2: Pulse test

Switching Time Test Circuit

(a) Test Circuit

(b) V_{IN}



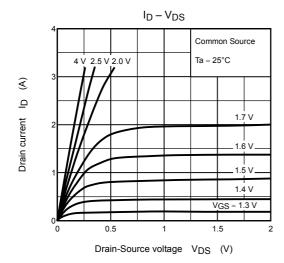
Precaution

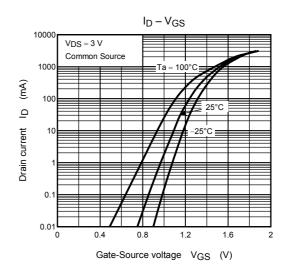
 V_{th} can be expressed as voltage between gate and source when low operating current value is $I_D = 100~\mu A$ for this product. For normal switching operation, V_{GS} (on) requires higher voltage than V_{th} and V_{GS} (off) requires lower voltage than V_{th} .

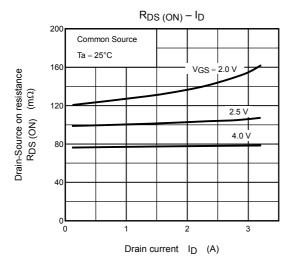
(Relationship can be established as follows: $V_{GS\ (off)}$ < V_{th} < $V_{GS\ (on)}$)

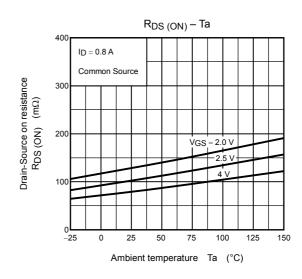
Please take this into consideration for using the device. V_{GS} recommended voltage of 2.5~V or higher to turn on this product.

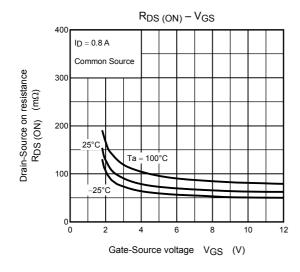
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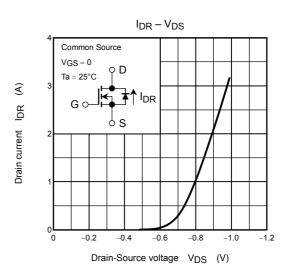


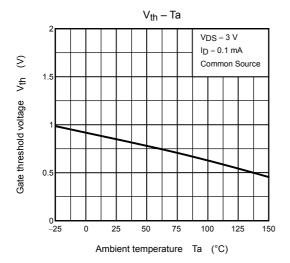


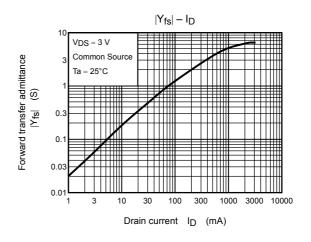


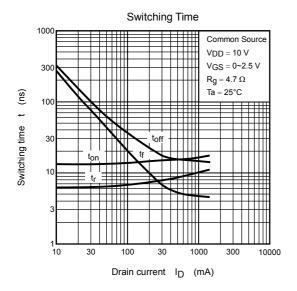


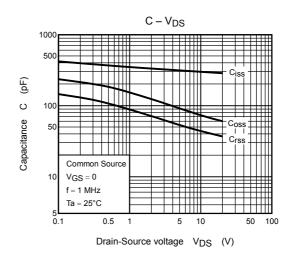


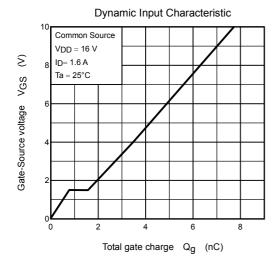


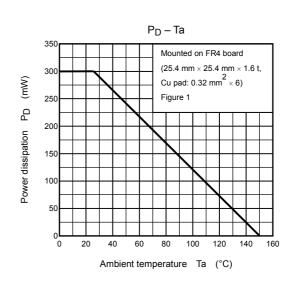




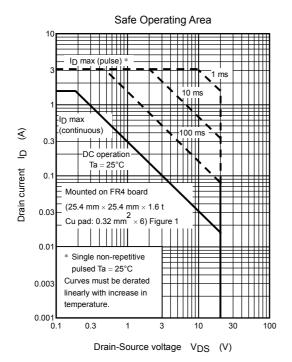


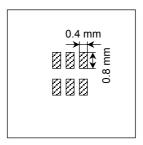






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25.4 mm \times 25.4 mm \times 1.6 t, Cu Pad: 0.32 mm $^2 \times 6$

Figure 1

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RESTRICTIONS ON PRODUCT USE

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